

C0402C222G3GEC7411

ESD SMD Comm COG, Ceramic, 2200 pF, 2%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0402



Click here for the 3D model.

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
S	0.3mm MIN
В	0.3mm +/-0.1mm

Packaging Specifications

Packaging Packaging Quantity

T&R, 330mm, Paper Tape 50000

General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	1.06 mg
Shelf Life	78 Weeks
MSL	1

Specifications		
Capacitance	2200 pF	
Measurement Condition	1 kHz 1.0Vrms	
Capacitance Tolerance	2%	
Voltage DC	25 VDC	
ESD Level per AEC-Q200	6,000 V ESD Level	
Dielectric Withstanding Voltage	62.5 VDC	
Temperature Range	-55/+125°C	
Temperature Coefficient	COG	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour	
Insulation Resistance	100 GOhms	

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